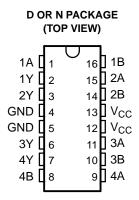
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SCLS054B-APRIL 1987-REVISED JUNE 2005

#### **FEATURES**

- Center-Pin V<sub>CC</sub> and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typ Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic 300-mil DIPs (N)



#### **DESCRIPTION**

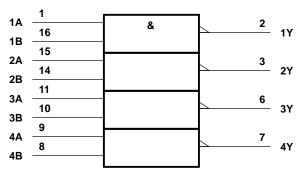
This device contains four independent 2-input NAND gates. It performs the Boolean function  $Y = \overline{A} \bullet \overline{B}$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

The 74AC11000 is characterized for operation from -40°C to 85°C.

# FUNCTION TABLE (EACH GATE)

INPL	JTS	OUTPUT
Α	В	Y
Н	Н	L
L	Χ	Н
X	L	Н

#### LOGIC SYMBOL(1)



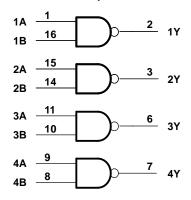
(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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### **LOGIC DIAGRAM (POSITIVE LOGIC)**



### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	7	V
VI	Input voltage range (2)		-0.5	V <sub>CC</sub> + 0.5	V
Vo	Output voltage range <sup>(2)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	$V_I < 0$ or $V_I > V_{CC}$		±20	mA
I <sub>OK</sub>	Output clamp current	$V_O < 0$ or $V_O > V_{CC}$		±50	mA
Io	Continuous output current	$V_O = 0$ to $V_{CC}$		±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
	Mayimum navar dissipation at T = EE°C (in atill siz)(3)	D package		1.3	W
	Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) <sup>(3)</sup>	N package		1.1	VV
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.



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### **Recommended Operating Conditions**

			MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage		3	5	5.5	V
		V <sub>CC</sub> = 3 V	2.1			
$V_{IH}$	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			V
		V <sub>CC</sub> = 5.5 V	3.85			
		V <sub>CC</sub> = 3 V			0.9	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35	V
		V <sub>CC</sub> = 5.5 V			1.65	
VI	Input voltage		0		$V_{CC}$	V
Vo	Output voltage		0		$V_{CC}$	V
		V <sub>CC</sub> = 3 V			-4	
I <sub>OH</sub>	High-level output current	$V_{CC} = 3 \text{ V}$ $V_{CC} = 4.5 \text{ V}$			-24	mA
		$V_{CC} = 5.5 \text{ V}$			-24	
		V <sub>CC</sub> = 3 V			12	
I <sub>OL</sub>	Low-level output current	$V_{CC} = 4.5 \text{ V}$			24	mA
		V <sub>CC</sub> = 5.5 V			24	
Δt/Δν	Input transition rise fall rate		0		10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40		85	°C

### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	T,	\ = 25°	С	MIN	MAY	UNIT
PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP	MAX	IVIIIN	WAX	UNII
		3 V	2.9			2.9		
	$I_{OH} = -50 \mu A$	4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
$V_{OH}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		V
	1 - 24 mA	4.5 V	3.94			3.8		
	$I_{OH} = -24 \text{ mA}$	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{(1)}$	5.5 V				3.85		
		3 V			0.1		0.1	
	$I_{OL} = 50 \mu A$	4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
$V_{OL}$	I <sub>OL</sub> = 12 mA	3 V			0.36		0.44	V
	1 - 24 mΛ	4.5 V			0.36		0.44	
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{(1)}$	5.5 V					1.65	
l <sub>l</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1		±1	μΑ
I <sub>cc</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		3.5				pF

<sup>(1)</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



### **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CC}$  = 3.3 V  $\pm$  0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	T,	<sub>A</sub> = 25°	С	MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	IVIAA	UNIT
t <sub>PLH</sub>	A or P	V	1.5	7.2	9.8	1.5	11.1	no
t <sub>PHL</sub>	A or B	Ť	1.5	5.8	8.6	1.5	9.6	ns

### **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CC}$  = 5 V  $\pm$  0.5 V (unless otherwise noted) (see Figure 1)

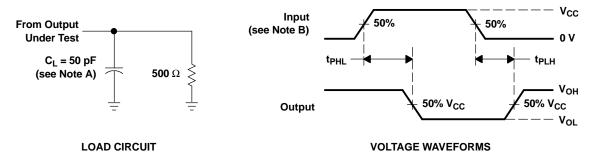
PARAMETER	FROM	то	T,	<sub>A</sub> = 25°	С	MIN	MAX	UNIT
PARAWIETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIV	IVIAA	UNIT
t <sub>PLH</sub>	A or B	V	1.5	5	6.5	1.5	7.4	
t <sub>PHL</sub>	AUID	Ť	1.5	4.4	6.1	1.5	6.8	ns

#### **Operating Characteristics**

 $V_{CC} = 5 \text{ V}, T_{A} = 25^{\circ}\text{C}$ 

	PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$	Power dissipation capacitance per gate	$C_L = 50 \text{ pF},  f = 1 \text{ MHz}$	33	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
	(-)	(=/			(-)	(4)	(5)		(-)
74AC11000D	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	-40 to 85	AC11000
74AC11000DR	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11000
74AC11000DR.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11000
74AC11000N	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	74AC11000N
74AC11000N.A	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	74AC11000N

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

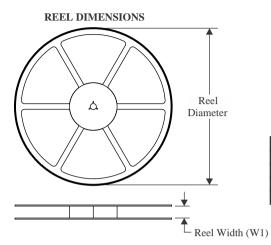
<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

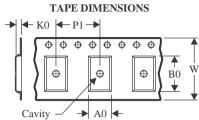
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

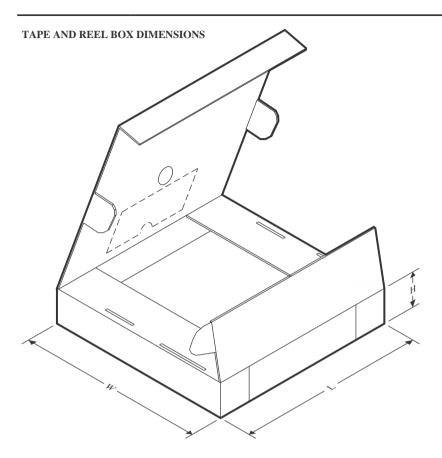
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC11000DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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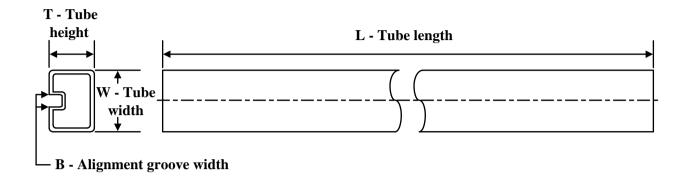
#### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	74AC11000DR	SOIC	D	16	2500	340.5	336.1	32.0

# **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**

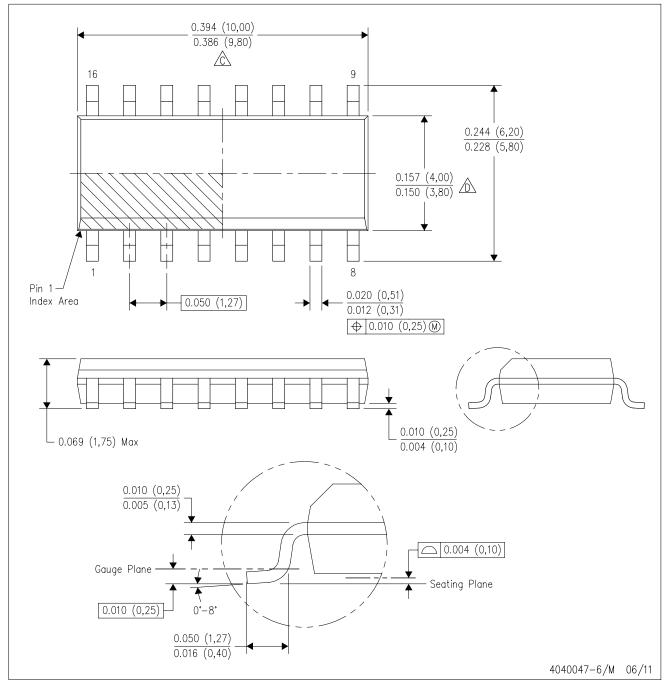


#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74AC11000N	N	PDIP	16	25	506	13.97	11230	4.32
74AC11000N	N	PDIP	16	25	506	13.97	11230	4.32
74AC11000N.A	N	PDIP	16	25	506	13.97	11230	4.32
74AC11000N.A	N	PDIP	16	25	506	13.97	11230	4.32

# D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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